

Product Texts

Zytel® HTN51G35HSLR BK420J is a 35% glass reinforced, heat stabilized, lubricated, hydrolysis resistant high performance polyamide resin with improved surface appearance. It is also a PPA resin.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.2 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.5 / *	%	ISO 294-4, 2577
^[C] Spec. heat capacity of melt	1820	J/(kg K)	-

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	11500 / -	MPa	ISO 527
^[C] Stress at break	215 / -	MPa	ISO 527
^[C] Strain at break	2.6 / -	%	ISO 527
^[C] Charpy notched impact strength, +23°C	11 / -	kJ/m ²	ISO 179/1eA
^[C] Charpy notched impact strength, -30°C	10 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Glass transition temperature, 10°C/min	135 / *	°C	ISO 11357-1/-2
^[C] Temp. of deflection under load, 1.80 MPa	264 / *	°C	ISO 75-1/-2
^[C] Coeff. of linear therm. expansion, parallel	18 / *	E-6/K	ISO 11359-1/-2
^[C] Coeff. of linear therm. expansion, normal	50 / *	E-6/K	ISO 11359-1/-2
^[C] Burning rate, FMVSS, Thickness 1 mm	23	mm/min	ISO 3795 (FMVSS 302)

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Volume resistivity	1E13 / -	Ohm*m	IEC 62631-3-1
^[C] Electric strength	34 / -	kV/mm	IEC 60243-1
^[C] Comparative tracking index	600 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Humidity absorption	1.4 / *	%	Sim. to ISO 62
^[C] Density	1460 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Chemical Resistance

Hydrolytically Stable

Additives

Lubricants

Regional Availability

North America, Europe, Asia Pacific, South and Central America

Special Characteristics

Heat stabilized or stable to heat

Other text information**Injection molding**

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

When lower mold temperatures are used, the initial warpage and shrinkage may be lower, but the surface appearance and chemical resistance may be reduced, and the dimensional change may be greater when parts are subsequently heated.